ABSTRACT

COMPRESSION MOLDING OF AN ELECTRONIC DEVICE

A compression molding system comprising first and second mold halves is provided for an electronic device wherein a plurality of cavities are formed in the first mold half corresponding to molding locations on the electronic device. A plurality of plungers are located in the first mold half, each of which is drivable against a side of a respective cavity for applying a compacting force to encapsulation material located in the cavity during molding. A motor is operatively connected to the plungers for driving the plungers relative to the cavities.

(FIG. 1)